

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10568147
<b>Filing Date:</b>	13-Feb-2006
<b>Title of Invention:</b>	Abrasive compounds for semiconductor planarization
<b>First Named Inventor/Applicant Name:</b>	Kanshi Chinone
<b>Filer:</b>	LEE C WRIGHT/Akemi Ferebee
<b>Attorney Docket Number:</b>	062110

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1110</b>